



RECOMMENDED P.C. BOARD LAYOUT
(TOL.±0.05;PCB T=0.90mm)(TOP VIEW)

- NOTE:
1. MATERIAL:
HOUSING:HIGE TEMP. THERMOPLASTIC,UL94V-0.
CONTACT: COPPER ALLOY,T=0.15;
TAB: COPPER ALLOY,T=0.20.
 2. FINISH:
CONTACT:
10U" MIN GOLD PLATING ON CONTACT AREA;
1U" MIN GOLD PLATING ON SOLDER TAILS;
50U"~180U" NICKEL UNDERPLATING OVERALL.
TAB:
40U" MIN HIGH TEMP. TIN PLATING ALL OVER;
20U" MIN NICKEL UNDERPLATING OVERALL.
 3. SPECIFICATION: SEE "2.5mm PITCH BATTERY 4PIN 4.0H PRODUCT SPEC".
 4. SOLDER HEAT RESISTANCE: REFLOW SOLDERING 260° FOR 10SEC.
 5. TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 6. HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
 7. HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKAGING:
 8. FOR REFLOW SOLDERING LEED FREE PROCESS.
 9. REPRESENT CRITICAL DIMENSIONS.
 10. CPK CONTROLLED DIMENSIONS.
 11. P/N RULES:

2BA2004-00 10 X 1 F

HALOGEN FREE(NEW P/N)
PACKAGE: TAPE AND REEL
HOUSING COLOR:
1: BLACK 2: GREEN(577C)
CONTACT FINISH:
Au 10U" MIN ON CONTACT AREA

REV.	ECN NO OR DESCRIPTION	REVISED	DATE
C	Alter the dimensional tolerance ECN: C080286	Steven-hu	2009.02.09
D	Rev. No. C100910-11	Baohua Ji	2010.02.27
E	ECN: C100608修改尺寸	LONGJIANG	2011.3.3

C	TAB	2	C2680-H.0.20T	5r. 40U"MIN, Ni: 20U"MIN.
B	CONTACT	4	C17200-TM04.0.15T	Au10U"AT CONTACT AREA
A	BODY	1	LCP E130;UL94V-0	SEE P/N RULES
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

DECIMALS:	ANGLES:	TITLE	2.5mm PITCH BATTERY 4PIN 4.0H
X : ±0.3	X : ±1°	DWN	Working DRAWING
X.X : ±0.2	X.X : ±0.5°	CHKD	22.110008
X.XX : ±0.1		APVD	100.110008
X.XXX : ±0.05		ENGINEERING COPY	